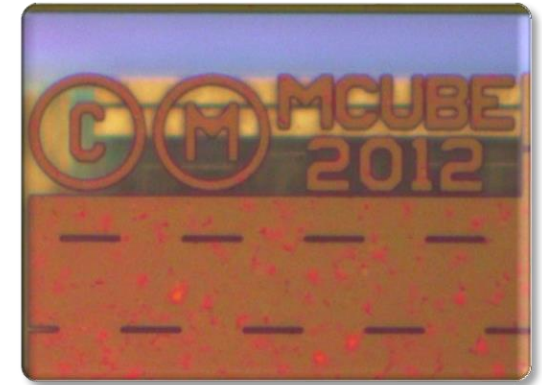
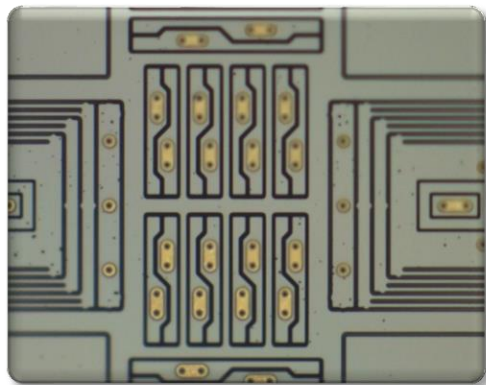




# MC3433

## 3-Axis Accelerometer



# Product Analysis Report

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